



Materials Declaration

Package	MQFP
Body Size	14 X 20
LeadCount	100
Option	Pb-Free



Molding Compound			
Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	1.23 E-01	62821
SiO2 Filler	84	1.03 E+00	527697
Phenol Resin	5.5	6.77 E-02	34552
Carbon Black	0.5	6.16 E-03	3141

Molding Compound		
Item	PPM	Method
Pb	4.40	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICPAes)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	4.34 E-01	221415
Ni	3	1.35 E-02	6905
Si	0.65	2.93 E-03	1496
Mg	0.15	6.77 E-04	345

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	2.0	EPA method 7196A & EPA 3060A

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100	3.00 E-03	1530

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100	2.11 E-02	10743

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	2.76 E-03	1410

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	2.33 E-01	118907

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	23	4.07 E-03	2079
Ag Filler	77	1.36 E-02	6959

Package Totals		
Weight (g)	PPM	
1.96 E+00	1000000	

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary





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Body Size	14 X 20
LeadCount	100
Option	Sn/Pb Plating



Molding Compound				
Item	% of Compound	Weight (g)	PPM	
Epoxy resin	10	1.23 E-01	62821	
SiO2 Filler	84	1.03 E+00	527697	
Phenol Resin	5.5	6.77 E-02	34552	
Carbon Black	0.5	6.16 E-03	3141	

Molding Compound		
Item	PPM	Method
Pb	4.40	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICPaes)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)

Leadframe				
Item	% of Leadframe	Weight (g)	PPM	
Cu	96.2	4.34 E-01	221415	
Ni	3	1.35 E-02	6905	
Si	0.65	2.93 E-03	1496	
Mg	0.15	6.77 E-04	345	

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	2.0	EPA method 7196A & EPA 3060A

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100	3.00 E-03	1530

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	1.79 E-02	9132
Pb	15	3.16 E-03	1611

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	2.76 E-03	1410

Chip			
	% of Chip	Weight (g)	PPM
Si	100	2.33 E-01	118907

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	23	4.07 E-03	2079
Ag Filler	77	1.36 E-02	6959

Package Totals	
Weight (g)	PPM
1.96 E+00	1000000

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